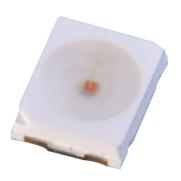


2T03X2SR00031SAA

Ultra high reliability and luminous efficacy ,PLCC LED Series are optimized to be used as lighting for automotive signal lighting designs or signboard.







I Applications:

- Automotive Interior/Exterior Lighting
- Traffic Lighting

— Signal Lighting

I Features:

- Package: Ag Plated 2 pad design package with silicone resin
- Dimension: 3.5 mmx2.8 mm
- Chip technology: AlGaInP
- View Angle: 120°
- Color: λ_{dom} =630 nm(Super Red)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- MSL: Level 2
- Qualifications: The product qualification test based on the guidelines of AEC-Q102



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General Information

Ordering Code Format

	X1	:	X2	X3	3-X4	X5	i-X6	×	7-X8
	Туре	Com	ponent	Se	eries	Wat	ttage	Col	or/CCT
2	Emitter	Т	PLCC	03	3528	X2	0.2W	SR	Super Red

X9->	(10	X11-	X12		X13	>	< 14		X15
CRI(Ra)	Volt	age	Leadfr	ame Mode	Leadfrai	me Plating	1	Model
00	-	03	3V	1	PCT 0.80H 2PIN	S	Silver	А	Automotive

X16 Serial Number



Absolute Maximum Ratings

Absolute maximum ratings

Parameter		Symbol	Values
Operating Temperature	min. max.	T _{op}	-40 °C 110 °C
Storage Temperature	min. max.	T_{stg}	-40 °C 110 °C
Junction Temperature	max.	T_{j}	125 °C
Forward current $T_J = 25 ^{\circ}\text{C}$	min. max.	I _F	5 mA 70 mA
Surge Current $t \le 10 \mu s$; $D = 0.005$; $T_j = 25 ^{\circ}C$	max.	I_{FS}	100 mA
Reverse voltage $T_J = 25 ^{\circ}\text{C}$	max.	V_R	10 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)		V_{ESD}	2 kV

Notes: Proper current derating must be observed to maintain junction temperature below the maximum at all time.

Characteristics

 $I_F = 50 \text{ mA}; T_J = 25 \text{ °C}$

Parameter		Symbol	Values
Peak Wavelength	typ.	λ_{Peak}	642 nm
Dominant Wavelength	min. typ. max.	$\lambda_{\sf dom}$	627 nm 630 nm 639 nm
Viewing angle	typ.	φ	120°
Forward Voltage	min. typ. max.	$V_{\scriptscriptstyle F}$	2.05 V 2.25 V 2.50 V
Reverse current $V_R = 10 \text{ V}$	typ. max.	I _R	0.01 μA 10 μA
Real thermal resistance junction/solder point	typ. max.	$R_{thJSreal}$	69 K / W 85 K / W
Electrical thermal resistance junction/ solder point with efficiency ne = 35 %	typ. max.	$R_{thJSelec.}$	45 K / W 55 K / W



Luminous Intensity Characteristic

Luminous Intensity Characteristics, I_F=50mA , T_J=25°C

Symbol	Group	Min. Luminous Intensity(mcd)	Max. Luminous Intensity(mcd)	Typ. Luminous Flux(mlm)
lv	AB	1400	1800	5000
IV	ВА	1800	2240	6312

Note:

The luminous intensity performance is guaranteed within published operating conditions. Edison Opto maintains a tolerance of $\pm 10\%$ on intensity measurements.

Voltage Bin Structure

Voltage Bin Structure, $I_F=50mA$, $T_J=25^{\circ}C$

Symbol	Group	Min. Voltage (V)	Max. Voltage (V)
	B05	2.05	2.20
V _F	B20	2.20	2.35
	B35	2.35	2.50

Note:

Forward voltage measurement allowance is \pm 0.1V.

Wavelength Bin Structure

Wavelength Bin Structure, I_F =50mA , T_J =25°C

Symbol	Group	Min. Wd (nm)	Max. Wd (nm)
,	S27	627	633
Λ _{dom}	S33	633	639

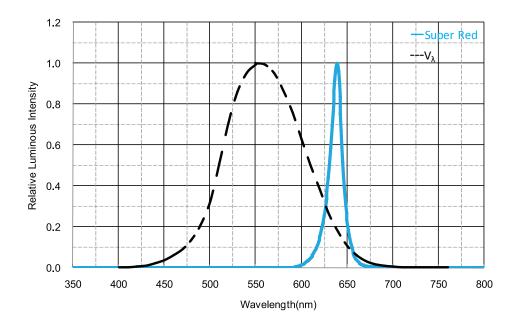
Dominant wavelength meansurement allowance is $\pm 1 \text{nm}$.



Characteristic Curves

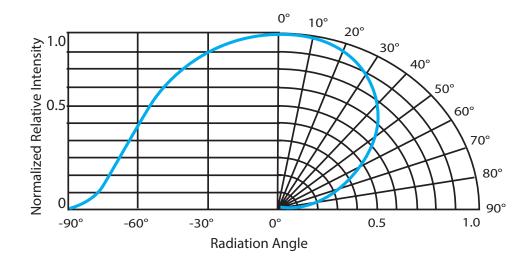
Color Spectrum

 $I_F = 50 \text{ mA} ; T_J = 25 \text{ °C}$



Beam Pattern

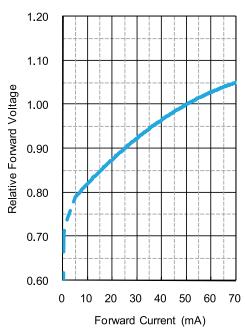
 $I_F = 50 \text{ mA}$; $T_J = 25 \,^{\circ}\text{C}$





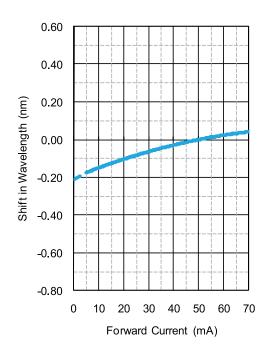
Relative Foward Voltage

 $V_F/V_F(50 \text{ mA}) = f(V_F); T_J = 25 \text{ °C}$



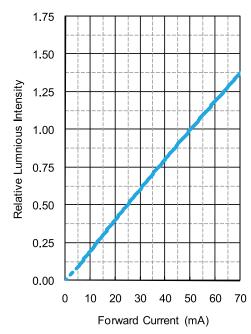
Shift in Dominant Wavelength

 $\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}$ (50 mA); $T_J = 25$ °C



Relative Luminous Intensity

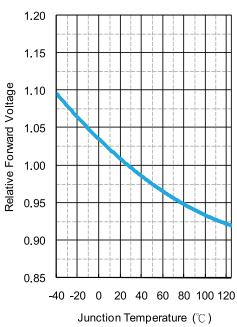
 $I_v/I_v(50 \text{ mA}) = f(I_v); T_v = 25 \text{ °C}$





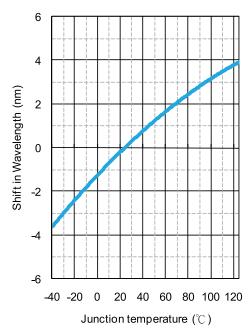
Relative Forward Voltage

 $V_F/V_F(25 \text{ °C}) = f(V_F); I_F = 50 \text{ mA}$



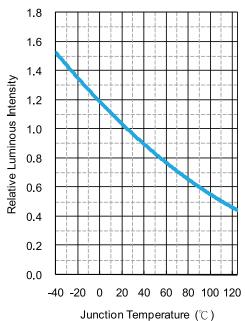
Shift in Dominant Wavelength

 $\Delta\lambda_{dom}$ = λ_{dom} - λ_{dom} (25 °C); I_F = 50 mA



Relative Luminous Intensity

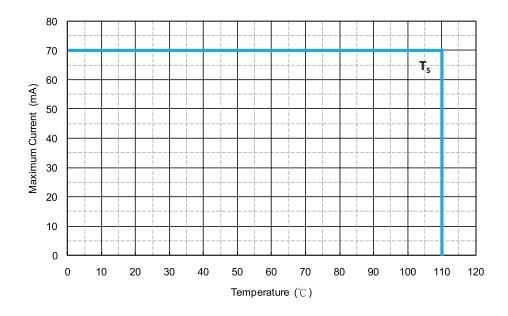
 $I_v/I_v(25 \text{ °C}) = f(I_v); I_F = 50 \text{ mA}$





Max. Permissible Forward Current

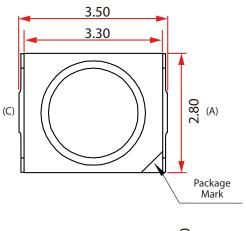
 $I_F = f(T)$

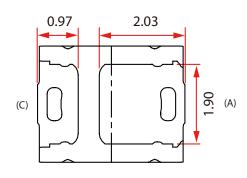


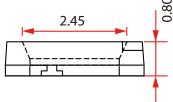


Mechanical Dimensions

Dimensional Drawing







Circuit



Notes:

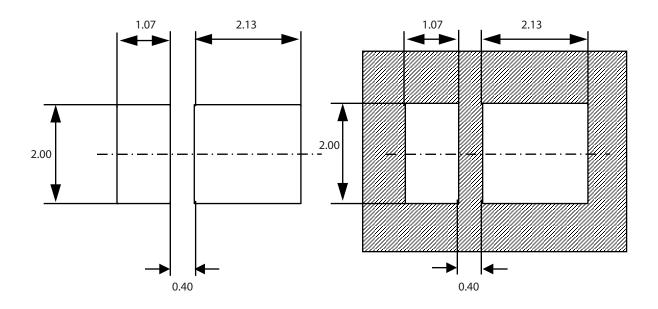
1. All dimensions are measured in mm.

2. Tolerance: ± 0.1 mm

3. Approximate Weight: 20.0 mg



Recommended Solder Pad



Paddesign for improved heat dissipation



Cu-area>16mm² per pad

Notes:

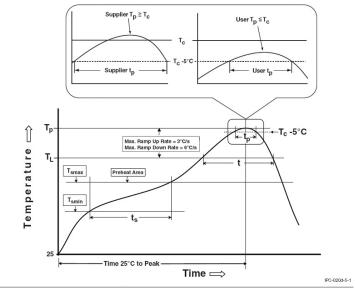
1. All dimensions are measured in mm.

2. Tolerance: ± 0.1 mm



Reflow Profile

The following reflow profile is from IPC/JEDEC J-STD-020D which provided here for reference.



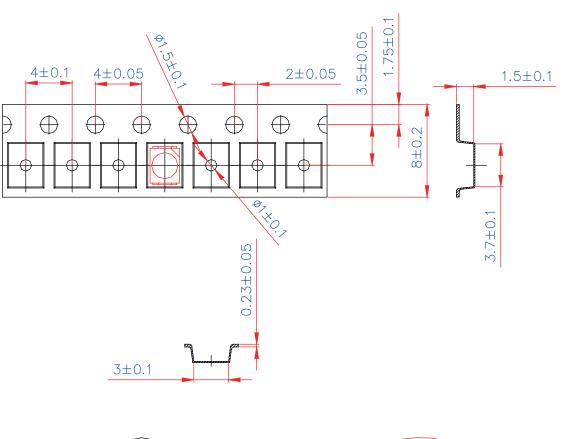
Reflow Profiles

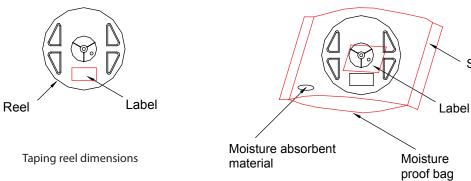
Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150 °C 200 °C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217 °C 60-150 seconds
Peak package body temperature (Tp)	255 °C ~260 °C
Classification temperature (Tc)	260 °C
Time (tp) within 5 °C of the specified classification temperature (Tc)	30 seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.



Product Packaging Information





Package & label

Item	Quantity	Total	Dimensions(mm)			
Reel	4,000pcs	4,000pcs	R=178			
Starting with 250pcs empty, and 150pcs empty at the last						

Seal



Cautions

- (1) Moisture monitoring is vital during the storage of LEDs for if too much moisture is absorbed, interface delamination and optical performance degradation will occur. Therefore, products should be packed in moisture-proof aluminum bags so as to reduce moisture absorption to the lowest degree during transportation and storage. Included moisture-proof aluminum bag are the key indicators that they will change from brown to azure if bags are invaded by moisture.
- (2) Soldering process in compliance with the range of the conditions stated above should be conducted after opening the moisture-proof aluminum bag. The rest LEDs should be stored in a hermetically sealed container, silica gel desiccants included. And the original moisture-proof aluminum bags are recommended.
- (3) If the "Period After Opening" storage time is too long or silica gel desiccants don't maintain blue any more, baking process should be done once.



Revision History

Versions	Description	Release Date
1	Establish a Datasheet	2023/01/08

About Edison Opto

Edison Opto is a leading manufacturer of high power LED and a solution provider experienced in LDMS. LDMS is an integrated program derived from the four essential technologies in LED lighting applications- Thermal Management, Electrical Scheme, Mechanical Refinement, Optical Optimization, to provide customer with various LED components and modules. More Information about the company and our products can be found at www.edison-opto.com

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